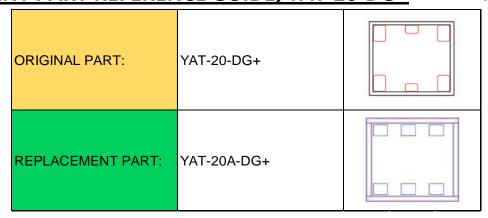


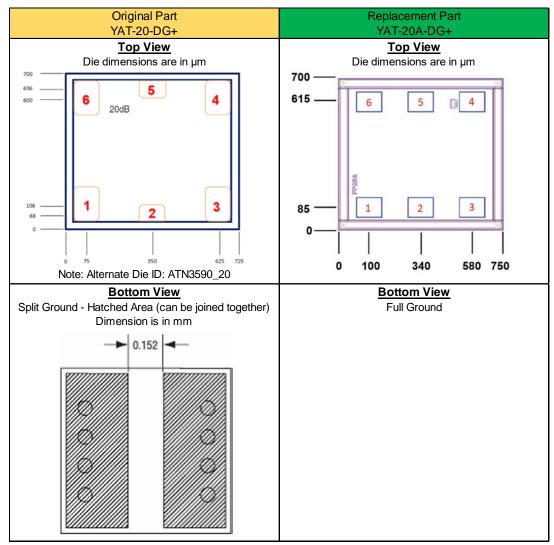
# **REPLACEMENT PART REFERENCE GUIDE, YAT-20-DG+**

AN-70-062



Replacement Part has been judged by Mini-Circuits Engineering as a suitable replacement to Original Parta

### **MECHANICAL DIMENSIONS**





<u>Dimensions</u>					
Parameter	Original Part YAT-20-DG+	Replacement Part YAT-20A-DG+			
Die Width, µm	725	750			
Die Length, µm	700	700			
Die Thickness, µm	100	100			
RF-IN & RF-OUT Bond Pad Size, µm	110 x 75	125 x 100			
Ground Bond Pad Size, µm	110 x 150	125 x 100			

	<u>Pin-Out</u>			
	Original Part	Replacement Part		
Pad#	YAT-20-DG+	YAT-20A-DG+		
	Function			
2	RF-IN	RF-IN		
5	RF-OUT	RF-OUT		
1,3,4,6	Ground	Ground		
Bottom of Die	Split Ground	Full Ground		
	-	-		

### **CONCLUSION:**

## 1) **FORM-FIT-FUNCTIONAL ANALYSIS**<sub>a</sub>:

The Replacement Part is Form, Fit compatible.

Following is a summary of changes/improvements in the Specification:

Parameter	Frequency (GHz)	Original Part	Replacement Part	
Attenuation Typ. (dB)	DC-5	20.1	20.0±0.1	
VSWR Typ. (:1)	DC-5	1.0	1.2	
Attenuation Typ. (dB)	5-15	20.2	20.0±0.1	
VSWR Typ. (:1)	2-13	1.1	1.2	
Attenuation Typ. (dB)	15-18	20.2	20.0±0.1	
VSWR Typ. (:1)	13-10	1.1	1.2	
Attenuation Typ. (dB)	18-26.5	20.5	19.9±0.3	
VSWR Typ. (:1)	16-20.5	1.2	1.2	
Max Power at 25°C (W)	DC-26.5	1.5	0.8	
Max Power at 85°C (W)	DC-26.5	1	0.6	

For typical performance and Graphs: See paragraphs 2 and 3

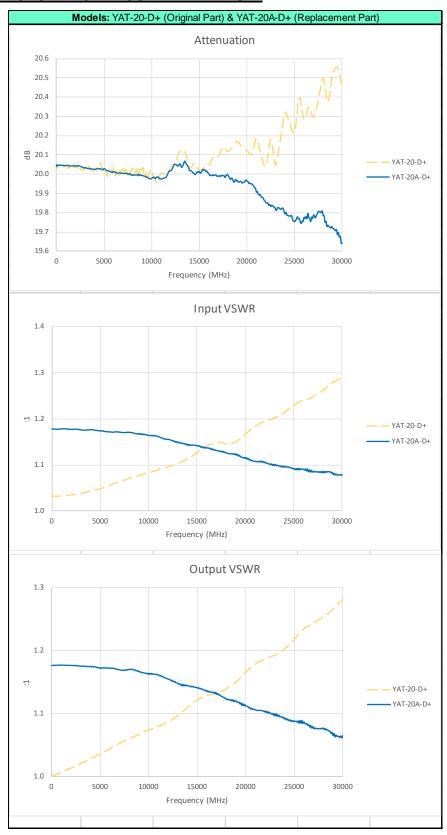
### 2) TYPICAL PERFORMANCE COMPARISON AT ROOM TEMPERATURE:

**MODEL:** YAT-20-DG+, YAT-20A-DG+ (RF Parameters)

Parameter		Freq (MHz)		5 Units of Original Part YAT-20-D+		3 Units of Replacement Part YAT-20A-D+		
	From	То	Min.	Avg.	Max.	Min.	Avg.	Max.
Insertion Loss (dB)	10	5000	20.01	20.04	20.06	20.02	20.04	20.05
	5000	15000	19.97	20.02	20.16	19.97	20.01	20.09
	15000	18000	20.02	20.09	20.17	19.98	20.00	20.04
	18000	26500	20.05	20.21	20.45	19.74	19.88	20.01
VSWR (:1)	10	5000	1.03	1.03	1.05	1.17	1.17	1.18
	5000	15000	1.04	1.06	1.13	1.14	1.16	1.17
	15000	18000	1.10	1.13	1.15	1.12	1.13	1.14
	18000	26500	1.12	1.17	1.24	1.08	1.10	1.13



### 3) TYPICAL PERFORMANCE GRAPHS AT ROOM TEMPERATURE:





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